

**Qualification of an Alternate Adhesive Material and Molding
Compound for Select LFCSP Packages**

Qualification Plan Summary for Multi Die LFCSP

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Jan 2023
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Jan 2023
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	Jan 2023
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	Jan 2023
Field Induced Charged Device Model Electrostatic Discharge (FICDM-ESD)	JEDEC <i>JS-002-2018</i>	3/Voltage	Jan 2023

* Preconditioned per JEDEC/IPC J-STD-020.